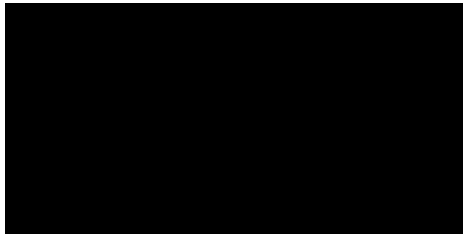




Small is Beautiful: Emerging Design Trends/Requirements for Rugged Small Form Factor

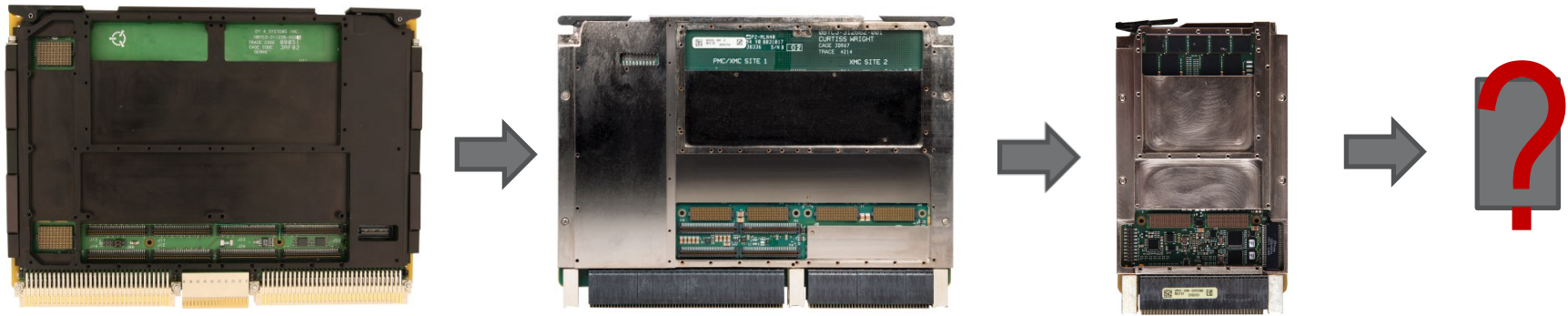


Agenda

- **SFF Definition**
- **Trends**
- **Use Cases**
- **Voice of Customer**
- **Requirements**
- **Review of VITA SFF Standards**
- **Summary**

Small Form Factor – How small?

- Certainly, <3U (differentiation, tech trends, packaging flexibility)
- Is 100 x 100mm (62.5% of 3U) small enough (i.e. to gain sufficient SWaP-C advantages)?
 - VITA 75.1 RSFF targeted 90 x 100mm “micro”VPX
- Target ~30-50% of 3U
 - With option to go smaller in the future (e.g. “postage stamp”)



Small Form Factor – How small?

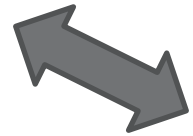
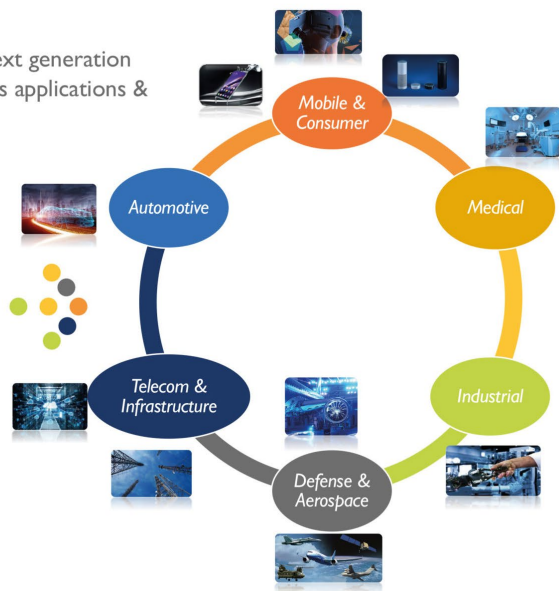
■ System/Subsystem Level

- 6U to 3U to ?
- Backplane to Carrier to ?
- ATR (& variants) to Custom (or VITA 75) to ?



Trends

5G, AI & IoT are 3 key trends driving the next generation semiconductor business, encompassing various applications & devices



Leading edge CMOS node (approx): 0.25um 0.18um 0.13um 90nm 65nm 40nm 28nm

- Miniaturization
- Integration
- I/O Density
- Functionality
- Power/Heat

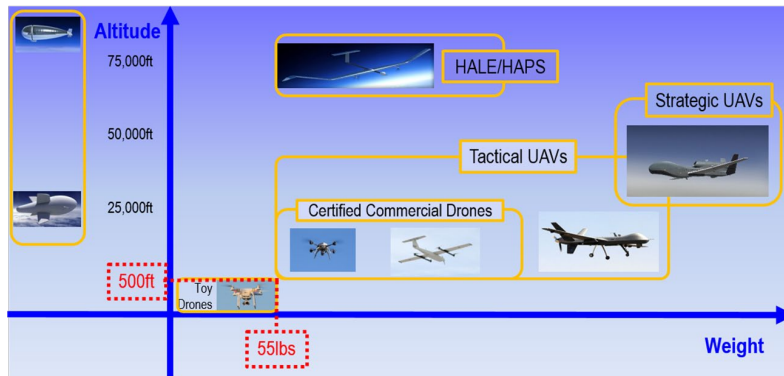
Courtesy: GM Systems



Use Cases



FAA Regulations (Dec-15) require UAVs > 55lb and operated >500ft to be certified to FAR Part 91



Safety Cert is a Key Driver for Rugged SFF



Voice of Customer

**“Extended
temperature range”**

**“SOLUTION FOR NEW
APPLICATIONS”**

**“Rugged interconnect
solution”**

“Up to D0-254 DAL A”

**“Small size, less
than half 3U”**

**“LONG-TERM
AVAILABILITY”**

**“Low
SWaP”**

**“low
power”**

“Low cost”

SFF Requirements

- **Module size ~30-50% of 3U**
- **Safety certifiable (up to DO-254 DAL A)**
- **Mil COTS ruggedness and reliability, e.g.**
 - -40 to 85+°C
 - VITA 47
 - VITA 72 vibration
- **Other “ilities” (e.g. availability, maintainability, supportability)**
- **Rugged interconnect solution (rugged connector)**
- **Flexible packaging approach (e.g. mezzanine, backplane, cabled)**

Current VITA SFF Standards

- **VITA 73 – VDSTU (VITA Draft Standard for Trial Use) in 2013; 3 WG members**
 - PCB size: 101.5mm x 71mm
 - Connector: TBD
- **VITA 74 – ANSI approved in 2017; 22 WG members**
 - PCB size: 84mm x 73mm (12.5mm module)
 - Connector: 200-pin (12.5mm module) or 400-pin (19mm module)
- **VITA 75 – VDSTU in 2012; 25 WG members**
 - PCB size: Agnostic or 100mm x 90mm (VITA 75.1)
 - Connector: Agnostic or VPX connector (VITA 75.1)

Summary

- **Use case and technology trends are driving a need for a SFF module size of 30-50% of 3U**
- **Diversity of use cases demands flexibility in SFF packaging**
- **Safety certifiability (DO-254, up to DAL A) is required**
 - Ruggedness and reliability are a must
- **There is a need for a new SFF module and standard**
 - Curtiss-Wright will be announcing a solution in 2020

Thank You

***CURTISS -
WRIGHT***

